Mohd Arif Anuar Mohd Salleh

List of Publications by Year
in descending order

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122 papers	1,206 citations	489802 18 h-index	536525 29 g-index
124 all docs	124 docs citations	124 times ranked	617 citing authors

#	Article	IF	Citations
1	The effect of Ni on the growth morphology of primary Î²-phase in an In-35Âwt%Sn alloy. Journal of Alloys and Compounds, 2022, 897, 163172.	2.8	7
2	Synthesis of Kaolin Geopolymer as Ceramic Reinforcement in Lead-Free Solder. Journal of Physics: Conference Series, 2022, 2169, 012019.	0.3	0
3	Controlling the distribution of porosity during transient liquid phase bonding of Sn-based solder joint. Materials Today Communications, 2022, 31, 103248.	0.9	1
4	Properties of Sn-3Âwt%Ag-5Âwt%Cu alloys with Cu6Sn5 intermetallics grain refined by Mg. Materials Today Communications, 2022, 31, 103221.	0.9	6
5	Formation and Growth of Intermetallic Compounds in Lead-Free Solder Joints: A Review. Materials, 2022, 15, 1451.	1.3	9
6	Recent Developments in Steelmaking Industry and Potential Alkali Activated Based Steel Waste: A Comprehensive Review. Materials, 2022, 15, 1948.	1.3	14
7	Liquid/Solid Interaction of Sn-58Bi/Sn-3.0Ag-0.5Cu Dissimilar Joints during Soldering at Low Temperature by In-Situ Synchrotron Imaging. Jom, 2022, 74, 2760-2769.	0.9	2
8	The Influence of Sintering Temperature on the Pore Structure of an Alkali-Activated Kaolin-Based Geopolymer Ceramic. Materials, 2022, 15, 2667.	1.3	16
9	Effect of Kaolin Geopolymer Ceramics Addition on the Microstructure and Shear Strength of Sn-3.0Ag-0.5Cu Solder Joints during Multiple Reflow. Materials, 2022, 15, 2758.	1.3	3
10	Origin of Primary Cu6Sn5 in Hypoeutectic Solder Alloys and a Method of Suppression to Improve Mechanical Properties. Journal of Electronic Materials, 2021, 50, 710-722.	1.0	9
11	A study of geo-polymer as alternative material in automotive brake pad. AIP Conference Proceedings, 2021, , .	0.3	1
12	Effects of Surface Finish on Sn-3.0Ag-0.5Cu Solder Joint Microstructure and Strength. Journal of Electronic Materials, 2021, 50, 855-868.	1.0	7
13	Microstructure evolution of Sn-Cu based solder paste on electroless nickel immersion gold (ENIG) surface finish subjected to multiple reflow cycles. AIP Conference Proceedings, 2021, , .	0.3	1
14	Effect of Ni on the Suppression of Sn Whisker Formation in Sn-0.7Cu Solder Joint. Materials, 2021, 14, 738.	1.3	5
15	The Effect of Thermal Annealing on the Microstructure and Mechanical Properties of Sn-0.7Cu-xZn Solder Joint. Metals, 2021, 11, 380.	1.0	0
16	Performance of Sn-3.0Ag-0.5Cu Composite Solder with Kaolin Geopolymer Ceramic Reinforcement on Microstructure and Mechanical Properties under Isothermal Ageing. Materials, 2021, 14, 776.	1.3	8
17	Influence of Sintering Temperature of Kaolin, Slag, and Fly Ash Geopolymers on the Microstructure, Phase Analysis, and Electrical Conductivity. Materials, 2021, 14, 2213.	1.3	7
18	Microstructure, thermal behavior and joint strength of Sn-0.7Cu-1.5Bi/electroless nickel immersion gold (ENIG). Journal of Materials Research and Technology, 2021, 12, 1700-1714.	2.6	8

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19	Microstructure, mechanical properties and corrosion analysis of Snâ€“0.7Cuâ€‰+â€‰Ga solders joints developed using green concentrated solar energy soldering method. Journal of Materials Science: Materials in Electronics, 2021, 32, 21709-21726.	1.1	2
20	Effect of Electromigration and Thermal Ageing on the Tin Whiskersâ€™ Formation in Thin Snâ€“0.7Cuâ€“0.05Ga Lead (Pb)-Free Solder Joints. Coatings, 2021, 11, 935.	1.2	7
21	Influence of 1.5 wt.% Bi on the Microstructure, Hardness, and Shear Strength of Sn-0.7Cu Solder Joints after Isothermal Annealing. Materials, 2021, 14, 5134.	1.3	3
22	The Effect of Ni and Bi Additions on the Solderability of Sn-0.7Cu Solder Coatings. Journal of Electronic Materials, 2020, 49, 1-12.	1.0	23
23	The effect of Bi on the microstructure, electrical, wettability and mechanical properties of Sn-0.7Cu-0.05Ni alloys for high strength soldering. Materials and Design, 2020, 186, 108281.	3.3	35
24	Effect of kaolin geopolymer ceramic addition on the properties of Sn-3.0Ag-0.5Cu solder joint. Materials Today Communications, 2020, 25, 101469.	0.9	12
25	Microstructure and porosity evolution of alkali activated slag at various heating temperatures. Journal of Materials Research and Technology, 2020, 9, 15894-15907.	2.6	22
26	Impact of Thermal Ageing and Multiple Reflow on Lead Free Composite Solder : A Short Review. IOP Conference Series: Materials Science and Engineering, 2020, 957, 012063.	0.3	0
27	Solidification Behaviour of Sn-40Pb Lead Solder and Sn-0.7Cu Lead-free Solder. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012036.	0.3	0
28	Microstructure and Mechanical Properties of Geopolymer Ceramic Reinforced Sn-0.7Cu Solder. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012041.	0.3	3
29	Bonding Strength Characteristics of FA-Based Geopolymer Paste as a Repair Material When Applied on OPC Substrate. Applied Sciences (Switzerland), 2020, 10, 3321.	1.3	29
30	Microstructure and growth kinetic study in Snâ€“Cu transient liquid phase sintering solder paste. Journal of Materials Science: Materials in Electronics, 2020, 31, 11077-11094.	1.1	7
31	Development of Geopolymer Ceramic as a Potential Reinforcing Material in Solder Alloy: Short review. IOP Conference Series: Materials Science and Engineering, 2020, 743, 012023.	0.3	2
32	Strength Development and Elemental Distribution of Dolomite/Fly Ash Geopolymer Composite under Elevated Temperature. Materials, 2020, 13, 1015.	1.3	42
33	Self-cleaning property of graphene oxide/TiO2 thin film. AIP Conference Proceedings, 2019, , .	0.3	7
34	Thermal behaviour and microstructural analysis of Sn-0.7Cu alloy and Sn-0.7Cu soldered on electroless nickel/immersion gold. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012023.	0.3	0
35	Fabrication of Novel Geopolymer Reinforced Tin Copper Solder in Suppressing Intermetallic Layer Growth. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012091.	0.3	2
36	Solderability of Sn-0.7Cu-0.05Ni-xZn Solder Ball on Sn-0.7Cu and Sn-0.7Cu-0.05Ni Solder Coating. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012094.	0.3	0

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37	Influence of kaolin geopolymer ceramic additions to the wettability and electrical properties of Sn-3.0Ag-0.5Cu (SAC305) lead free solder. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012033.	0.3	5
38	The Effect of Geopolymer Ceramic Additions to The Wettability and Shear strength of Sn-Ag-Cu (SAC) Solder: A Preliminary Study. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012081.	0.3	6
39	Relationship between free solder thickness to the solderability of Snâ€“0.7Cuâ€“0.05Ni solder coating during soldering. Journal of Materials Science: Materials in Electronics, 2019, 30, 3669-3677.	1.1	14
40	Characterising the polymorphic phase transformation at a localised point on a Cu6Sn5 grain. Materials Characterization, 2018, 138, 113-119.	1.9	37
41	Influence of Bi Addition on Wettability and Mechanical Properties of Sn-0.7Cu Solder Alloy. Solid State Phenomena, 2018, 273, 27-33.	0.3	12
42	Solidification Behavior of Sn Cu Based Peritectic Alloys: A Short Review. Solid State Phenomena, 2018, 273, 34-39.	0.3	1
43	The Effect of Aggressive Corrosion Mediums on the Microstructure and Properties of Mild Steel. IOP Conference Series: Materials Science and Engineering, 2018, 374, 012044.	0.3	0
44	Sn Whiskers Nucleation and Growth - Short Review. Solid State Phenomena, 2018, 280, 175-180.	0.3	1
45	Enhancement of Microstructural and Physical Properties of Sn-0.7Cu Lead-Free Solder with the Addition of SiC Particles. Solid State Phenomena, 2018, 280, 181-186.	0.3	0
46	The Effect of Copper Addition on the Properties of Sn-0.7Cu Solder Paste. IOP Conference Series: Materials Science and Engineering, 2018, 318, 012062.	0.3	1
47	Protection of Tempered Aluminum Alloy in Contact with the Environment. IOP Conference Series: Materials Science and Engineering, 2018, 374, 012043.	0.3	0
48	Imaging the Polymorphic Transformation in a Single Cu6Sn5 Grain in a Solder Joint. Materials, 2018, 11, 2229.	1.3	15
49	The Effects of Gallium Additions on the Microstructure of Lead-Free Solder Materials: A Short Review. Solid State Phenomena, 2018, 280, 187-193.	0.3	3
50	Corrosion Protection Of Mild Steel In Sea Water Using Chemical Inhibitor. IOP Conference Series: Materials Science and Engineering, 2018, 343, 012012.	0.3	6
51	Microstructure Evolution of Sn-Cu Based Solder Paste with Different Cu Concentration Subjected to Multiple Reflows. Solid State Phenomena, 2018, 280, 206-211.	0.3	3
52	The Effect of Temperature on Tin Whisker Growth under Mechanical Stress. Solid State Phenomena, 2018, 280, 194-199.	0.3	2
53	Microstructure, Interfacial IMC and Wettability of Sn-0.7Cu-xZn Solder Alloy. Solid State Phenomena, 2018, 280, 157-162.	0.3	0
54	Spontaneous Tin (Sn) Whisker Growth from Electroplated Tin and Lead-Free Tin Alloys Coatings: A Short Review. Solid State Phenomena, 2018, 280, 151-156.	0.3	3

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55	Influence of Ni on the refinement and twinning of primary Cu6Sn5 in Sn-0.7Cu-0.05Ni. Intermetallics, 2018, 102, 34-45.	1.8	27
56	Phase study of titanium dioxide nanoparticle prepared via sol-gel process. IOP Conference Series: Materials Science and Engineering, 2018, 343, 012011.	0.3	14
57	Synchrotron Radiography of Sn-0.7Cu-0.05Ni Solder Solidification. Solid State Phenomena, 2018, 273, 66-71.	0.3	2
58	In situ imaging of microstructure formation in electronic interconnections. Scientific Reports, 2017, 7, 40010.	1.6	43
59	Thermal and mechanical properties of Sn-Cu-Ni-XSiC composite solder. AIP Conference Proceedings, 2017, , .	0.3	1
60	Real time X-ray imaging of soldering processes at the SPring-8 synchrotron. , 2017, , .		0
61	Effects of Bi in Sn-Cu based lead-free solder alloys and interconnects. , 2017, , .		7
62	Effect of silicon (Si) particles addition on melting temperature, intermetallic compound formation and solderability of Sn-Cu-Ni composite solder paste. AIP Conference Proceedings, 2017, , .	0.3	0
63	Microstructural and phase analysis of Sn-Cu-Ni-XSiC composite solder. AIP Conference Proceedings, 2017, , .	0.3	1
64	Nickel (Ni) Microalloying Additions in Sn-Cu Lead-free Solder. Short Review. IOP Conference Series: Materials Science and Engineering, 2017, 209, 012084.	0.3	2
65	Microstructure and mechanical properties of lead-free Sn-Cu-Ni composite solder paste reinforced with silicon (Si) particles. AIP Conference Proceedings, 2017, , .	0.3	2
66	Effects of Ni and TiO2 additions in as-reflowed and annealed Sn0.7Cu solders on Cu substrates. Journal of Materials Processing Technology, 2017, 242, 235-245.	3.1	54
67	Effect of Zinc Additions on Sn-0.7Cu-0.05Ni Lead-Free Solder Alloy. IOP Conference Series: Materials Science and Engineering, 2017, 238, 012012.	0.3	4
68	An Investigation of TiO2Addition on Microstructure Evolution of Sn-Cu-Ni Solder Paste Composite. MATEC Web of Conferences, 2016, 78, 01070.	0.1	3
69	Suppression of Cu 6 Sn 5 in TiO 2 reinforced solder joints after multiple reflow cycles. Materials and Design, 2016, 108, 418-428.	3.3	57
70	Influence of Activated Carbon Particles on Intermetallic Compound Growth Mechanism in Sn-Cu-Ni Composite Solder. MATEC Web of Conferences, 2016, 78, 01064.	0.1	1
71	Effect of TiO 2 additions on Sn-0.7Cu-0.05Ni lead-free composite solder. Microelectronics Reliability, 2016, 65, 255-264.	0.9	54
72	In Situ TEM Observations of Cu6Sn5 Polymorphic Transformations in Reaction Layers Between Sn-0.7Cu Solders and Cu Substrates. Jom, 2016, 68, 2871-2878.	0.9	23

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73	Wettability and Shear Strength of Sn-Cu-Ni-xSi₃N₄ Composite Solder. Key Engineering Materials, 2016, 700, 152-160.	0.4	6
74	The influence of ageing on the stabilisation of interfacial (Cu,Ni)6(Sn,Zn)5 and (Cu,Au,Ni)6Sn5 intermetallics in Pb-free Ball Grid Array (BGA) solder joints. Journal of Alloys and Compounds, 2016, 685, 471-482.	2.8	37
75	Effect of Ni on the Formation and Growth of Primary Cu6Sn5 Intermetallics in Sn-0.7Âwt.%Cu Solder Pastes on Cu Substrates During the Soldering Process. Journal of Electronic Materials, 2016, 45, 154-163.	1.0	51
76	The Effect of Dipping Time to the Intermetallic Compound and Free Solder Thickness of Sn-Cu-Ni (SN100C) Lead-Free Solder Coating. Applied Mechanics and Materials, 2015, 754-755, 493-497.	0.2	4
77	Microstructural Observation and Phase Analysis of Sn-Cu-Ni (SN100C) Lead Free Solder with Addition of Micron-Size Silicon Nitride (Si₃N₄) Reinforcement. Applied Mechanics and Materials, 2015, 754-755, 518-523.	0.2	7
78	In Situ Soldering Process Technique by Synchrotron X-Ray Imaging. Applied Mechanics and Materials, 2015, 754-755, 508-512.	0.2	3
79	Development of a microwave sintered TiO2 reinforced Snâ€“0.7wt%Cuâ€“0.05wt%Ni alloy. Materials and Design, 2015, 82, 136-147.	3.3	43
80	Rapid Cu6Sn5 growth at liquid Sn/solid Cu interfaces. Scripta Materialia, 2015, 100, 17-20.	2.6	56
81	The Root Caused Analysis of Leakaged Heat Exchanger Tube. Praktische Metallographie/Practical Metallography, 2015, 52, 157-176.	0.1	1
82	Thermal Properties of Sn-0.7Cu/re-Al Composite Lead-Free Solder. Advanced Materials Research, 2013, 795, 451-454.	0.3	0
83	Preparation of Cyclopentyl Trisilanol Silsesquioxanes - Modified Natural Rubber (CpSSQ(OH)₃ ENR-50) Composite Hybrid in the Presence of HCL Acid. Advanced Materials Research, 2013, 795, 251-255.	0.3	2
84	Failure Investigation on Rusty Mesh Strainer of Petrochemical Plant. Advanced Materials Research, 2013, 795, 488-491.	0.3	1
85	Compressive Strength and Morphology of Fly Ash Based Geopolymer as Artificial Aggregate with Different Curing Temperature. Key Engineering Materials, 2013, 594-595, 151-155.	0.4	5
86	Thermal Properties of Different Recycled Acrylonitrile-Butadiene Rubber Glove (NBRr) Size and its Blend Ratios on SBR/NBRr Blends. Advanced Materials Research, 2013, 795, 377-382.	0.3	7
87	The Effect of Different Sizes "Batu Reput" (Dolomite) as a Filler in SMR L and ENR-50. Advanced Materials Research, 2013, 795, 383-387.	0.3	3
88	High Temperature Creep and Hydrogen Embrittlement Failure of a Steam Trap Bypass Tube. Advanced Materials Research, 2013, 795, 455-458.	0.3	0
89	Natural Rubber/Styrene Butadiene Rubber/Recycled Nitrile Glove (NR/SBR/rNBRg) Ternary Blend: Curing Characteristics and Swelling Test. Key Engineering Materials, 2013, 594-595, 634-638.	0.4	3
90	Overview of Pathogenic Micro-Organisms Destruction in Contaminated Water by Oxide Photocatalysis. Advanced Materials Research, 2013, 795, 483-487.	0.3	0

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91	Alteration of Solution Treatment Condition to the Precipitation Behavior A319 Alloy. Advanced Materials Research, 2013, 795, 679-683.	0.3	1
92	Research Development of Solder Materials and its Intermetallic Compound (IMC) Study. Advanced Materials Research, 2012, 626, 797-801.	0.3	0
93	Research Advances of Composite Solder Material Fabricated via Powder Metallurgy Route. Advanced Materials Research, 2012, 626, 791-796.	0.3	6
94	Characterization of Sn-3.5Ag-1.0Cu Lead-Free Solder Prepared via Powder Metallurgy Method. Advanced Materials Research, 2012, 501, 160-164.	0.3	3
95	Intermetallic evolution between Sn-3.5Ag-1.0Cu-xZn lead free solder and copper substrate under long time thermal aging (x: 0, 0.1, 0.4, 0.7). , 2012, , .		0
96	Solder microstructure and intermetallic interface evaluation between Sn-3.5Ag-1.0Cu-xNi lead free solder under long time thermal aging (x: 0, 0.05, 0.2, 0.5). , 2012, , .		0
97	Mechanical properties of Snâ€“0.7Cu/Si3N4 lead-free composite solder. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2012, 556, 633-637.	2.6	76
98	Solderability of Sn-0.7Cu/Si3N4 lead-free composite solder on Cu-substrate. Physics Procedia, 2011, 22, 299-304.	1.2	48
99	Wettability, Electrical and Mechanical Properties of 99.3Sn-0.7Cu/Si₃N₄ Novel Lead-Free Nanocomposite Solder. Advanced Materials Research, 0, 277, 106-111.	0.3	23
100	FT-IR and Morphology of Different Recycled Acrylonitrile-Butadiene Rubber Glove (NBRgr) Size and its Blend Ratios of SBR/NBRr Blends. Advanced Materials Research, 0, 626, 1033-1037.	0.3	0
101	Intermetallic Compound Formation on Solder Alloy/Cu-Substrate Interface Using Lead-Free Sn-0.7Cu/Recycled-Aluminum Composite Solder. Advanced Materials Research, 0, 620, 105-111.	0.3	18
102	Microstructure Evolution of Sn-3.5Ag-1.0Cu-0.5Ni/Cu System Lead Free Solder under Long Term Thermal Aging. Advanced Materials Research, 0, 620, 263-267.	0.3	1
103	The Effects of Tensile and Morphological Properties of Styrene Butadiene Rubber/Recycled Chloroprene Rubber (SBR/CRr) Blends. Advanced Materials Research, 0, 626, 802-806.	0.3	0
104	Zn-Sn Based High Temperature Solder - A Short Review. Advanced Materials Research, 0, 795, 518-521.	0.3	25
105	Effect of Aging Time towards Intermetallic Compound (IMC) Growth Kinetics Formation for Sn-0.7Cu-Si₃N₄ Composite Solder on Copper Substrate. Advanced Materials Research, 0, 795, 505-508.	0.3	1
106	Synthesis and Characterization of Electroless Copper Coated SiC Particles. Advanced Materials Research, 0, 795, 233-236.	0.3	1
107	Mixing Optimization of Sn-Cu-Si₃N₄ via Powder Metallurgy Route for Composite Solder Fabrication. Key Engineering Materials, 0, 594-595, 765-769.	0.4	0
108	Effect of Aging Temperature on the Intermetallic Compound (IMC) Formation of Sn-0.7Cu/Si₃N₄ Composite Solder. Advanced Materials Research, 0, 795, 522-525.	0.3	1

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109	Fabrication of Cu-SiC_p Composites via the Electroless Copper Coating Process for the Electronic Packaging Applications. Advanced Materials Research, 0, 795, 272-275.	0.3	1
110	Metallurgical Failure Analysis of a Closed Recirculation System Water Cooling Pipe. Advanced Materials Research, 0, 795, 474-478.	0.3	0
111	Effects of Recycled-Aluminum Additions on the Mechanical Properties of Sn-0.7Cu/Cu-Substrate Lead-Free Solder Joints. Advanced Materials Research, 0, 795, 446-450.	0.3	3
112	Non-Metal Reinforced Lead-Free Composite Solder Fabrication Methods and its Reinforcing Effects to the Suppression of Intermetallic Formation: Short Review. Applied Mechanics and Materials, 0, 421, 260-266.	0.2	27
113	The Effect of Different Alkaline Treatment Condition on Flexural Properties of Kenaf Bast-Unsaturated Polyester Composite. Advanced Materials Research, 0, 795, 631-634.	0.3	2
114	Low and High Temperature Isothermal Aging Effect on Morphology and Diffusion Kinetics of Intermetallic Compound (IMC) for Sn-Cu-Si₃N₄ Composite Solder. Key Engineering Materials, 0, 594-595, 666-670.	0.4	2
115	Isothermal Aging Affect to the Growth of Sn-Cu-Ni-1 wt.% TiO₂ Composite Solder Paste. Key Engineering Materials, 0, 700, 123-131.	0.4	9
116	Effect of TiO₂ on the Formation of Primary and Interfacial Cu₆Sn₅ in Sn-0.7wt%Cu and Sn-0.7wt%Cu-0.05wt%Ni Solder Paste during Soldering. Key Engineering Materials, 0, 700, 161-169.	0.4	5
117	Grain Refinements of Cu₆Sn₅ in Sn-3wt%Ag-5wt%Cu High Temperature Solder Alloys. Solid State Phenomena, 0, 273, 20-26.	0.3	1
118	Influence of Non-Metallic Particles Addition on Wettability, Intermetallic Compound Formation and Microhardness of Sn-0.7Cu Lead Free Solder Paste. Solid State Phenomena, 0, 280, 169-174.	0.3	8
119	Growth Kinetic of Sn-0.7Cu-0.05Ni Solder Paste Subjected to Isothermal Aging. Solid State Phenomena, 0, 280, 163-168.	0.3	5
120	Effect of Zn Additions on Thermal and Mechanical Properties of Sn-0.7Cu-xZn Solder Alloy. Solid State Phenomena, 0, 280, 200-205.	0.3	1
121	Effect of rare-element (Ga) addition on the microstructure and mechanical properties of Sn-0.7Cu and Sn-0.7Cu-0.05Ni lead-free solder alloys. IOP Conference Series: Materials Science and Engineering, 0, 701, 012031.	0.3	3
122	Effects of immersion silver (ImAg) and immersion tin (ImSn) surface finish on the microstructure and joint strength of Sn-3.0Ag-0.5Cu solder. Journal of Materials Science: Materials in Electronics, 0, , .	1.1	2